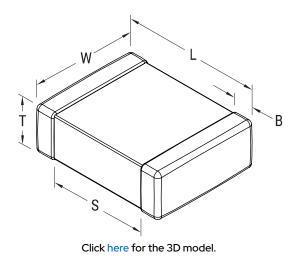


C2220C183G1TACTU

Aliases (C2220C183G1TAC7800)

SMD Comm X8G HT150C, Ceramic, 0.018 uF, 2%, 100 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 2220, 3.5 mm



General Information		
Series	SMD Comm X8G HT150C	
Style	SMD Chip	
Description	SMD, MLCC, High Temperature, Ultra-Stable	
Features	High Temperature, Ultra-Stable	
RoHS	Yes	
Termination	Tin	
Marking	No	
AEC-Q200	No	
Typical Component Weight	190 mg	
Shelf Life	78 Weeks	
MSL	1	

0.018 uF

Dimensions	
Chip Size	2220
L	5.7mm +/-0.4mm
W	5mm +/-0.4mm
Т	1.4mm +/-0.15mm
S	3.5mm MIN
В	0.6mm +/-0.35mm

W	5mm +/-0.4mm
Т	1.4mm +/-0.15mm
S	3.5mm MIN
В	0.6mm +/-0.35mm
Packaging Specifications	

L	5.7mm +/-0.4mm	Measurement Condition	1 kHz 1.0Vrms
W	5mm +/-0.4mm	Tolerance	2%
Т	1.4mm +/-0.15mm	Voltage DC	100 VDC
S	3.5mm MIN	Dielectric Withstanding Voltage	250 VDC
В	0.6mm +/-0.35mm	Temperature Range	-55/+150°C
		Temp. Coefficient	X8G
Packaging Specifications		Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Packaging	T&R, 180mm, Plastic Tape		
Packaging Quantity 1000	Dissipation Factor	0.1% 1 kHz 1.0Vrms	
		Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
		Insulation Resistance	55.5556 GOhms

Specifications Capacitance

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